

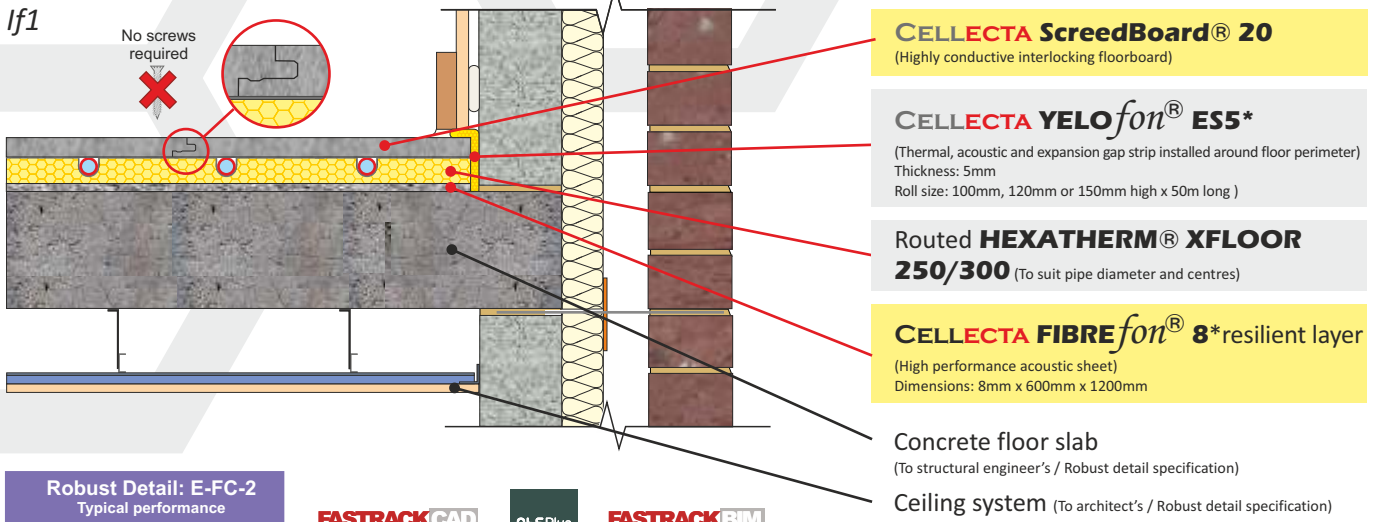
INTERMEDIATE CONCRETE FLOOR



CELLECTA **ScreedBoard® 20** installed on routed **CELLECTA HEXATHERM® XFLOOR 250/300**

CELLECTA FIBREfon® resilient layer installed below UFH thermal insulation board

Building Regulations Part E Solution



Product Information

ScreedBoard® 20

- Low thermal resistance, providing quick response times for under floor heating system
- No screws required - interlocking edge detail
- High density dry board - No wet trades
- Robust detail E-FC-1 & 2 and E-FS-1 compliant**

Physical Properties

	ScreedBoard® 20
Thermal Conductivity EN 12667 (W/mK)	0.50
Board dimension (mm)	20 x 600 x 1200
Weight	25.00kg/m ² - 18.00kg/per sheet

*Not applicable under Q Mark Certification **When used in conjunction with **FIBREfon 8**

Product Information



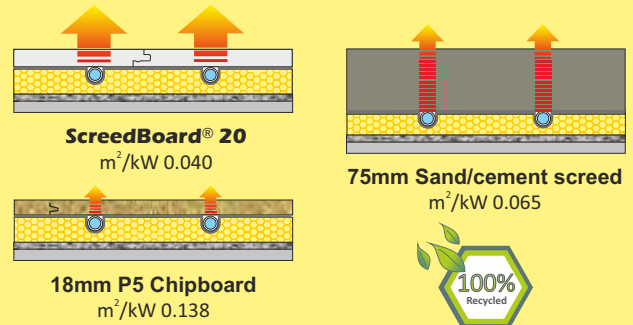
- ⬢ Excellent life-long thermal performance
- ⬢ High compressive strength
- ⬢ Closed cell structure, ideal for routing

Physical Properties

		XFLOOR	
		250	300
Thermal Conductivity EN 12667 (W/mK)	≤80mm	0.033	0.033
	≥81mm	-	0.034
Temperature range		-50/+75 °C	-50/+75 °C
Thickness' (mm) (other sizes manufactured to order)		20 25 30	40 50 60 75 80 100 120 140 160

Premium Thermal Performance

ScreedBoard 20 has a low thermal resistance when compared to the other commonly used floor finishes, allowing, boilers, ground water heat pumps and heat recovery systems to work at maximum efficiency.



Third Party Accreditation and Approvals



Environmental Credentials



Code for Sustainable Homes

Pol 1	HEXATHERM XPS boards
GWP value	<5
Code credits	1

Note: Pol.1 Code credits have an approximate weighted value of 0.7